

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

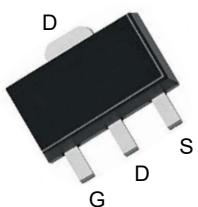
Product Summary



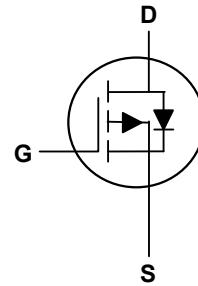
V_{DS}	-30	V
I_D	-4	A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	52	mΩ
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	90	mΩ

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



SOT89 Top View



Absolute Maximum Ratings($T_A=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D @ T_A=25^\circ C$	-4	A
Continuous Drain Current ¹	$I_D @ T_A=70^\circ C$	-3	A
Pulsed Drain Current ²	I_{DM}	-20	A
Total Power Dissipation ³	$P_D @ T_A=25^\circ C$	1.32	W
Total Power Dissipation ³	$P_D @ T_A=70^\circ C$	0.84	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹ (Steady State)	$R_{\theta JA}$	---	95	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	30	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	---	---	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.023	---	$\text{V}/^\circ\text{C}$
Static Drain-Source On-Resistance ²	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}$, $I_D=-4\text{A}$	---	---	52	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_D=-2\text{A}$	---	---	90	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = -250\mu\text{A}$	-1.2	---	-2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		---	4	---	$\text{mV}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-5\text{V}$, $I_D=-4\text{A}$	---	11	---	S
Total Gate Charge	Q_g	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_D=-4\text{A}$	---	6.4	---	nC
Gate-Source Charge	Q_{gs}		---	2.3	---	
Gate-Drain Charge	Q_{gd}		---	1.9	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_G=3.3\Omega$, $I_D=-4\text{A}$	---	2.8	---	ns
Rise Time	T_r		---	8.4	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	39	---	
Fall Time	T_f		---	6	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	583	---	pF
Output Capacitance	C_{oss}		---	100	---	
Reverse Transfer Capacitance	C_{rss}		---	80	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ^{1,4}	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	-4.5	A
Pulsed Source Current ^{2,4}	I_{SM}		---	---	-23	A
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V
Reverse Recovery Time	t_{rr}	$I_F=-4\text{A}$, $di/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	7.8	---	nS
Reverse Recovery Charge	Q_{rr}		---	2.5	---	nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

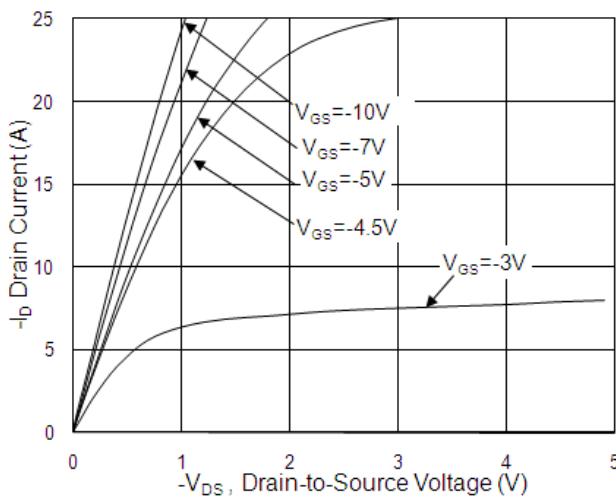


Fig.1 Typical Output Characteristics

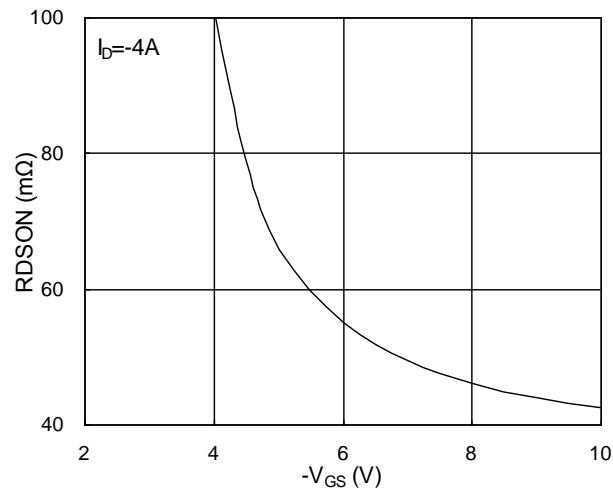


Fig.2 On-Resistance vs. Gate-Source

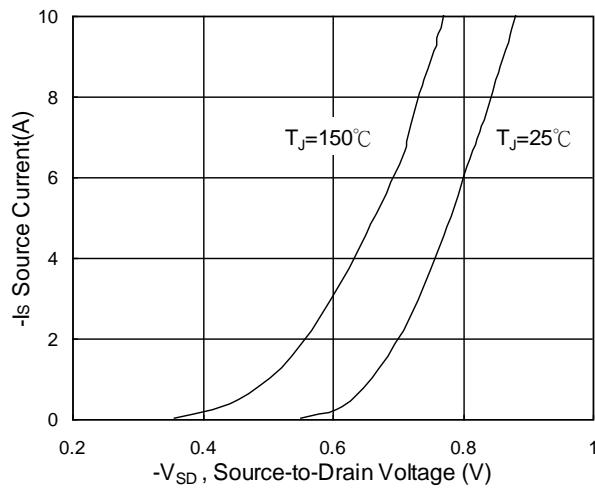


Fig.3 Forward Characteristics of Reverse

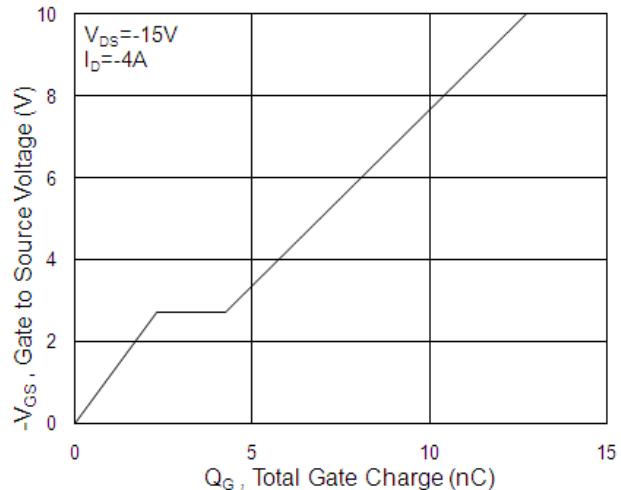


Fig.4 Gate-Charge Characteristics

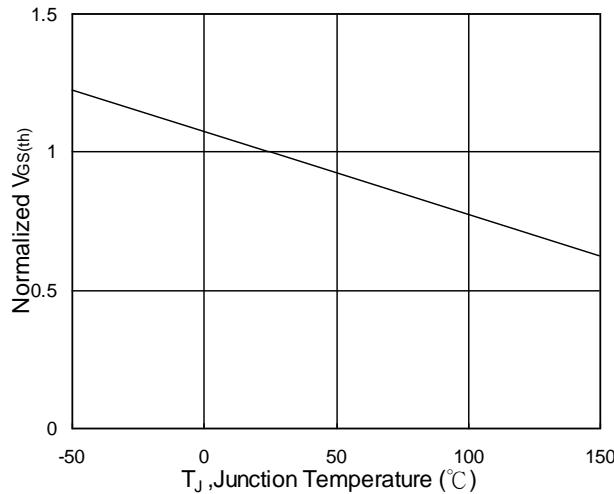


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

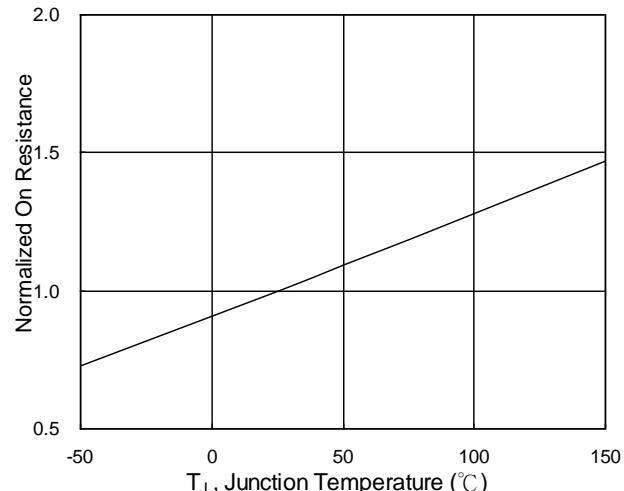
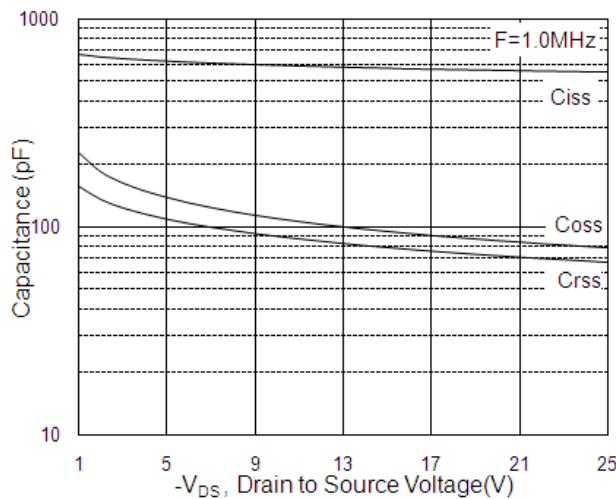
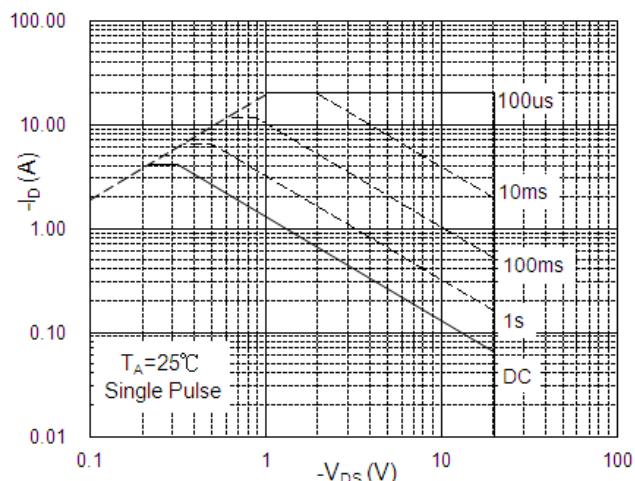
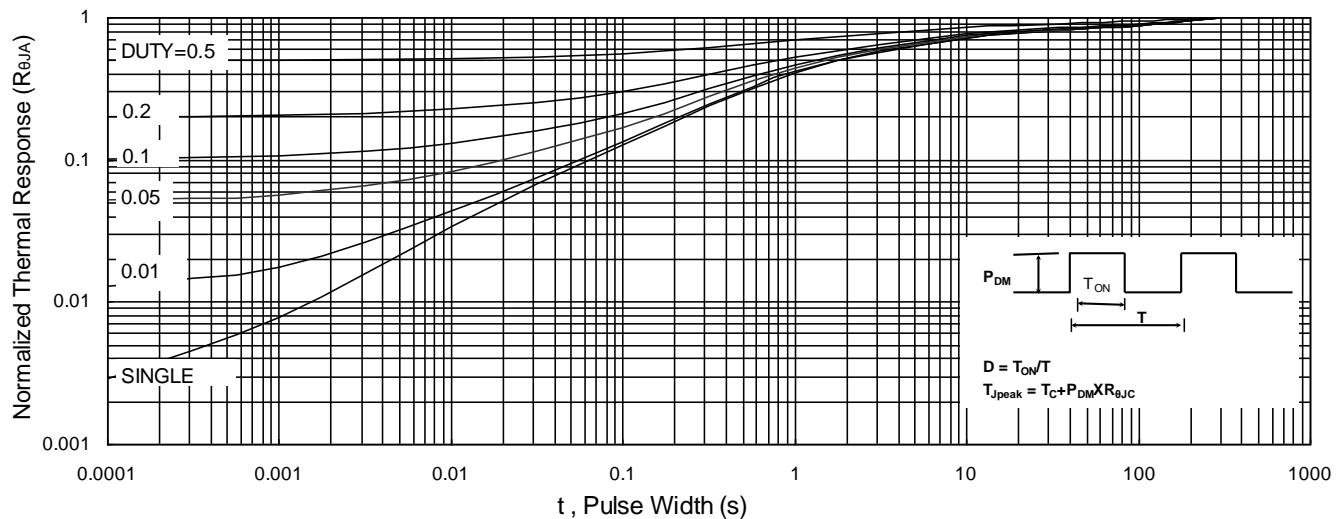
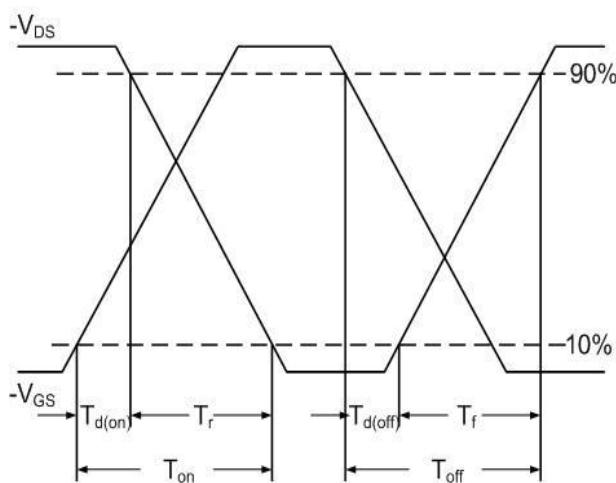
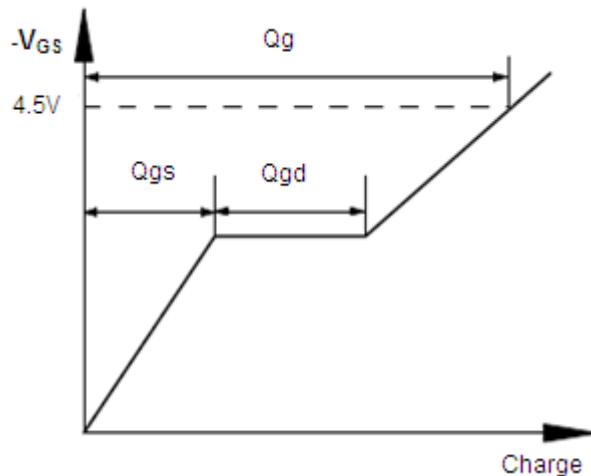
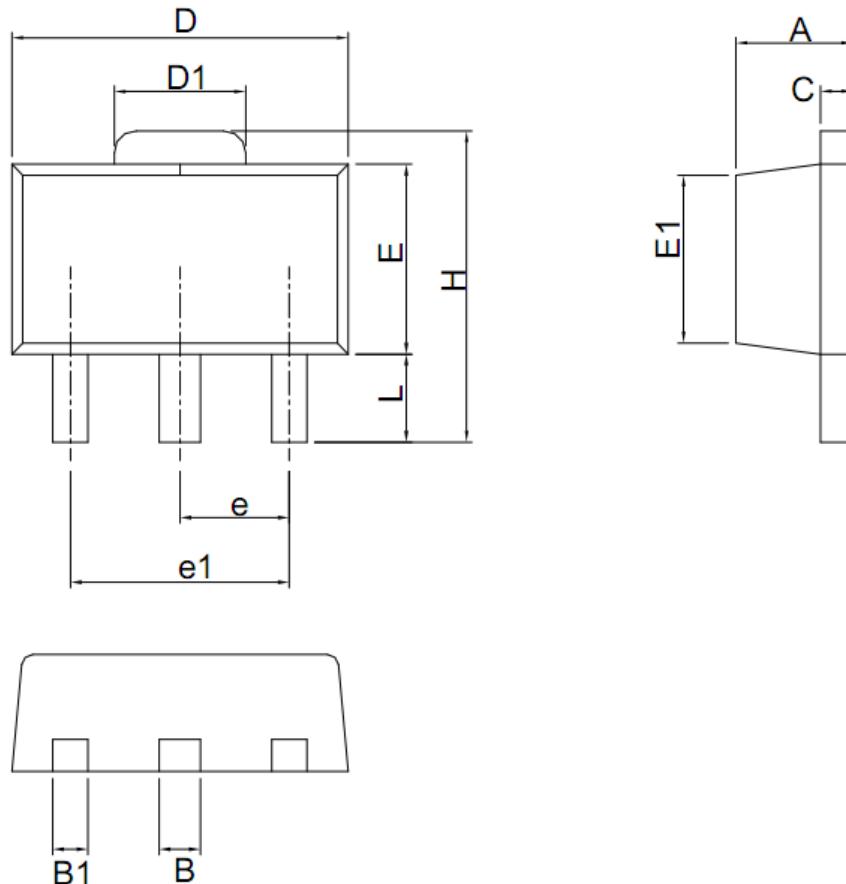


Fig.6 Normalized R_{DSON} vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

SOT89 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	1.40	1.50	1.60	E	2.40	2.50	2.60
B	0.40	0.50	0.56	E1	2.10	2.20	2.30
B1	0.32	0.40	0.50	e	1.50 BSC		
C	0.35	0.40	0.44	e1	3.00 BSC		
D	4.40	4.50	4.60	H	3.94	4.10	4.25
D1	1.40	1.60	1.80	L	0.85	1.00	1.20